g GE Energy	**Functional Testing Specification**
Parts & Repair Services ***Louisville, KY***	**LOU-GED-DS200DTBA**

Test Procedure for a DS200DTBAG1A

DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column

REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial release	G. Chandler	12/17/2013
B			
C			

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G. Chandler			Charlie Wade
DATE	**DATE**	**DATE**	**DATE**
12/17/2013			12/17/2013

1. SCOPE

1.1 This is a functional testing procedure for a DS200DTBAG1A.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
3.1.1 Check board's electronic folder for more information

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning
4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.
4.2 Equipment Inspection
4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
4.2.1.1 Wires - broken, cracked, or loosely connected
4.2.1.2 Terminal strips / connectors - broken or cracked
4.2.1.3 Components - visually damaged
4.2.1.4 Capacitors - bloated or leaking
4.2.1.5 Solder joints - damaged or cold
4.2.1.6 Circuit board - burned or de-laminated
4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 87 DMM (or Equivalent)
1		

6. Testing Process

6.1 Testing Procedure

6.1.1 Verify J12-1 and J12-2 are open (> 1M ohm) to chassis ground.

6.1.2 Verify 150k ohms (+/- 5%) between J12-1 and J12-2.

6.1.3 Verify 150k ohms (+/- 5%) between JY-1 and JY-2.

6.1.4 Verify J12-1 to JQR-2, JQS-2 and JQT-2 is open (> 1M ohm).

6.1.5 Verify J12-2 to JQR-3, JQS-3 and JQT-3 is open (> 1M ohm).

6.1.6 Verify JQR-3, JQS-3 and JQT-3 is 10 ohms (+/- 5%) to chassis ground.

6.1.7 Apply +24Vdc to JQR-1, JQS-1 and JQT-1 with common to JQR-50, JQS-50 and JQT-50.

6.1.8 Verify J12-1 to JQR-2, JQS-2 and JQT-2 is 750K ohms (+/- 5%).

6.1.9 Verify J12-2 to JQR-3, JQS-3 and JQT-3 is < 1 ohm.

6.1.10 Verify JQR-3, JQS-3 and JQT-3 is open (> 1M ohm) to chassis ground.

6.1.11 Remove 24Vdc supply from card.

6.1.12 Insure all jumpers BJ1-BJ5 are in.

6.1.13 Verify < 1 ohm between J12-1 and all of the even numbered terminal connection 2-92.

6.1.14 Verify 150k ohms (+/-5%) between J12-2 and all of the odd numbered terminal connections 1-91.

6.1.15 Using the schematic diagram, verify 750K ohm (+/- 5%) between the odd numbered terminal connections and the corresponding JQR, JQS and JQT connectors.

6.1.16 Normal repairs; Burn card in for 1 hours and verify steps 6.1.7 thru 6.1.11 are still within tolerances.

6.1.17 **All Revitalization Cards shall be burned-in for three (3) hours, check text box in SAP to determine if they fall into this category.**

6.2 ***TEST COMPLETE ***

7. Attachments

7.1 None at this time.